

IN THE CLAIMS:

Listing of the claims:

52. (Previously Presented) A socket contact formation process, comprising:
forming a contact head from a conductive material;
forming a contact body from a semiconductive material configured to be electrically conductive;
and
joining said contact head and said contact body.

53. (Original) The process in claim 52, wherein:
said step of forming a contact head comprises stamping a metal element;
said step of forming a contact body comprises etching silicon; and
said step of joining said contact head and said contact body further comprises adhering said
contact head onto said contact body.

54. (Original) The process in claim 52, wherein said step of joining said contact head
and said contact body further comprises depositing a metal over a silicon surface.